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TI Cladding materials for sputtering targets  
IN Ishikura, Chiharu  
PA Tanaka Noble Metal Industrial Co., Ltd., Japan  
SO Jpn. Kokai Tokkyo Koho, 3 pp.  
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AB The material is made of Cu >99.7%, and Zn, In, Mn, Sb, Be, Ca, Cr, Te, Y, Nb, Mo, Ta, and/or Sn 100-3000 ppm for separation of the backing plate in exchange of the target and efficient cooling.